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APPARATUS AND SEMICONDUCTOR
MANUFACTURING EQUIPMENT***C23C 14/50* (2006.01)*C23C 14/54* (2006.01)*H01J 37/32* (2006.01)(52) **U.S. CL.**CPC *H01J 37/3435* (2013.01); *C23C 14/34*
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Provided is a consumable component treating apparatus for ensuring coating thickness uniformity and a semiconductor manufacturing equipment including the same. The consumable component treating apparatus comprises a housing; a process gas providing unit for providing process gas to an interior of the housing; a plasma generating unit including a high-frequency power source and for generating plasma inside the housing using the process gas; a holder for fixing a base material; a metal substrate for supporting the holder; and a support module for supporting a target material coated on a base material using the plasma.

